

LEADED

# BGA SOLDER PASTE



Sn63/Pb37

Melting point 183°C



## Product Usage

● ● ●  
TIN PASTE

|               |              |
|---------------|--------------|
| Type number   | BST-503-JP   |
| Types of      | Solder Paste |
| Composition   | Sn63/Pb37    |
| Melting point | 183°C        |
| G.W.          | 70g          |
| size          | 1.41*1.28 in |



Sn63/Pb37

Melting point at medium temperature

183°C





Low residue



Solder spot bright



Rapid welding

# Welding requirements for a wide range of products



SMT  
patch



LED  
patch



BGA  
welding



# Product List

G.W.:70g

